

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



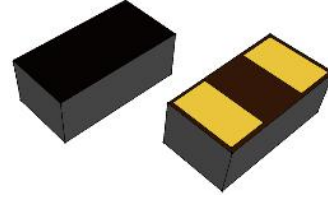
PLED

Product data sheet

Features

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<10nA)
- Fast response time(<1ns)
- Bi-directional, single line protection
- IEC 61000-4-2 (ESD Air): 15kV
IEC 61000-4-2 (ESD Contact): 8kV

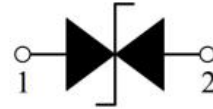
Pin Description



Applications

- USB 3.0/3.1
- HDMI 1.3/1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Schematic Diagram



Order Information

Type	Package	Size (mm)	Delivery Form	Delivery Quantity
MSPESD04DMA05	0402	1.00x0.52x0.38	7" T&R	10,000

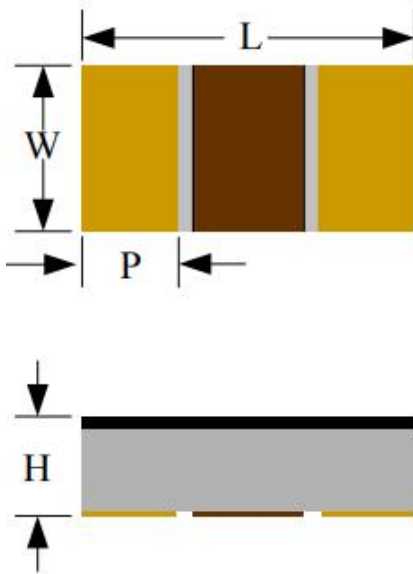
Limiting Values(T_A = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	8	kV
		IEC 61000-4-2; Air Discharge	-	15	kV
T _A	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-40	85	°C

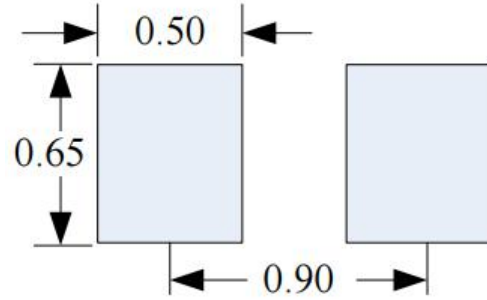
Electrical Characteristics(T_A = 25 °C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V _{DC}	Continuous Operating Voltage	-	-	-	5.0	V
V _T	Trigger Voltage	IEC61000-4-2 8kV contact discharge	-	450	-	V
V _C	Clamping Voltage	IEC61000-4-2 8kV contact discharge	-	40	-	V
I _L	Leakage Current	DC 5V shall be applied on component	-	-	10	nA
C _J	Capacitance	Measured at 10MHz	-	0.05	-	pF

Package Dimension



Recommended Solder Pad Footprint



***Sizes in mm**

Notes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters	
	Min.	Max.
L	0.90	1.10
W	0.42	0.62
p	0.15	0.35
H	0.25	0.45

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